

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HO MAN CHENG	09/07/2021
YAO CHENG LIANG	09/07/2021
KA HO MUI	09/07/2021
RECEIVING PARTY DATA	
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17467664
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DATE SIGNED:	09/13/2021
Total Attachments: 4	
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ASSIGNMENT OF INVENTION

WHEREAS, **HO MAN CHENG**, (a citizen of Hong Kong SAR) whose address is 3/F Photonics Center, 2 Science Park East Avenue, Hong Kong Science Park, Shatin, NT, Hong Kong, **YAO CHENG LIANG**, (a citizen of the People's Republic of China) whose address is 3/F Photonics Center, 2 Science Park East Avenue, Hong Kong Science Park, Shatin, NT, Hong Kong, **KA HO MUI**, (a citizen of Canada) whose address is Flat G, 33/F, Block 5, Kingsford Terrace, Wong Tai Sin, Kowloon, Hong Kong, are the inventors (hereinafter referred to as **ASSIGNORS**) of certain new and useful improvements in

A CAMERA CALIBRATION METHOD

WHEREAS, **ASSIGNORS** are now the exclusive owner of said application and the **INVENTION** described and claimed therein, and all rights in, to and under the same; and

WHEREAS, **HONG KONG APPLIED SCIENCE AND TECHNOLOGY RESEARCH INSTITUTE CO., LTD.**, a corporation organized under the laws of Hong Kong, whose address is 3/F Building 6, 2 Science Park West Avenue, Hong Kong Science Park, Shatin, New Territories, Hong Kong, (hereinafter referred to as **ASSIGNEE**), is desirous of acquiring the entire right, title and interest in and to the aforementioned application and **INVENTION** and in, to and under any and all Letters Patent of the United States and in any and all foreign countries thereof;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, **ASSIGNORS** have sold, assigned, transferred and set over and do hereby sell, assign, transfer and set over to the said **ASSIGNEE**, the said **INVENTION** and application, and any and all divisions and continuations thereof, and any and all Letters Patent of the United States, its territorial possessions, and any and all foreign countries which may be granted therefore, and any and all reissues and reexaminations of said Letters Patent, including the subject matter of any and all claims which may be obtained in every such patent, the same to be held and enjoyed by the said **ASSIGNEE** for its own use and behoof, and for the use and behoof of its successors, assigns, or other legal representatives, to the end of the term or terms for which said Letters Patent of the United States, territories and foreign countries are or may be granted, reissued, or reexamined as fully and entirely as same would have been held and enjoyed by **ASSIGNORS**, as if this assignment and sale had not been made.

AND, **ASSIGNORS** hereby authorize and request the Commissioner of Patents to issue any and all Letters Patent of the United States on said **INVENTION**, or resulting from said application, and from any and all divisions and continuations thereof to the said **ASSIGNEE**, of the entire interest, and hereby covenants that they have full right to convey the entire interest therein assigned, and that they have not executed and will not execute any agreement in conflict therewith.


AND, **ASSIGNORS** further hereby covenant and agree that they will, at any time, upon request, at the expense of said **ASSIGNEE**, execute and deliver any and all papers that may be necessary or desirable to perfect the title to said **INVENTION**, and to said Letters Patent as may be granted therefore, in said **ASSIGNEE**, its successors, assigns, or other legal representatives, and that if said **ASSIGNEE**, its successors, assigns, or other legal representatives shall desire to

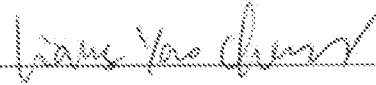
file any divisional or continuation application, or to secure a reissue or reexamination of such Letters Patent, or to file a disclaimer relating thereto, will, upon request, sign all papers, make all rightful oaths, and do all acts requisite for the filing of such divisional or continuing application, or such application for reissue or reexamination and procuring thereof, and for the filing of such disclaimers, without further compensation, but at the expense of said ASSIGNEE, its successors or other legal representatives.

AND, ASSIGNORS do further covenant and agree, that they will, at any time, upon request, communicate to said ASSIGNEE, its successors, assigns, or other legal representatives, at its expense, such facts relating to said INVENTION and Letters Patent or the history thereof, as may be known to them, and testify as to the same in any interference or other litigation, when requested to do so.

IN WITNESS WHEREOF, we have hereunto set our hands upon the day of signing as noted below:

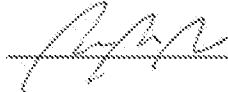
SIGNATURES

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Third Named Inventor: **KA HO MUI**

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